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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/689,824	10/13/2000	Takaaki Sasaki	PNET.011D	7074

7590 12/21/2001
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EXAMINER

BERRY, RENEE R

ART UNIT PAPER NUMBER

2818

DATE MAILED: 12/21/2001

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary

Application No.
09/689,824

Applicant(s)
Sasaki

Examiner
Renee Berry

Art Unit
2818



-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136 (a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on Oct 10, 2001
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11; 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 7-23 is/are pending in the application.
- 4a) Of the above, claim(s) 16-23 is/are withdrawn from consideration.
- 5) ☒ Claim(s) 7-15 is/are allowed.
- 6) ☐ Claim(s) _____ is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claims _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are objected to by the Examiner.
- 11) ☐ The proposed drawing correction filed on _____ is: a) ☐ approved b) ☐ disapproved.
- 12) ☐ The oath or declaration is objected to by the Examiner.

Priority under 35 U.S.C. § 119

- 13) ☐ Acknowledgement is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d).
- a) ☐ All b) ☐ Some* c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. _____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- *See the attached detailed Office action for a list of the certified copies not received.
- 14) ☐ Acknowledgement is made of a claim for domestic priority under 35 U.S.C. § 119(e).

Attachment(s)

- 15) ☐ Notice of References Cited (PTO-892)
- 16) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 17) ☐ Information Disclosure Statement(s) (PTO-1449) Paper No(s) _____
- 18) ☐ Interview Summary (PTO-413) Paper No(s) _____
- 19) ☐ Notice of Informal Patent Application (PTO-152)
- 20) ☐ Other: _____

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DETAILED ACTION

Election/Restriction

1. Applicant's election without traverse of Group I in Paper No. 7 is acknowledged.
2. Claims 16-23 are withdrawn from further consideration pursuant to 37 CFR 1.142(b) as being drawn to a nonelected invention, there being no allowable generic or linking claim. Election was made **without** traverse in Paper No. 7.

Claim Objections

3. Claims 7-9 are objected to because of the following informalities: "through hall". The correct term is "**through hole**". Appropriate correction is required.

Claim Rejections - 35 USC § 102

4. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless --

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371© of this title before the invention thereof by the applicant for patent.

5. Claims 7-15 are rejected under 35 U.S.C. 102(e) as being anticipated by US patent no. 6,268,648 to Fukutomi et al.

Fukutomi teaches a method of making a semiconductor package comprising preparing a semiconductor package structure by providing a substrate for mounting a semiconductor element

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thereon to fix a semiconductor element to one side thereof and a connecting pattern provide on the other side of the substrate and by forming a through hole from the one side to the other side of the substrate; fixing a surface where the element is formed of a semiconductor element on the one side of the substrate of the semiconductor package such that an electrode of the semiconductor element is within the through hole; electrically connecting a connecting pattern and an electrode of a semiconductor element via wires through the through hole; and sealing the through hole and wires with resin at column 6, lines 30-44.

In regard to claim 8, Fukutomi teaches a connecting pattern is provided continuously in a plurality of stages and an end portion of connecting pattern on the side of the through hole is provided on a stage on the side of the one side of the substrate at column 8, lines 43-55.

In regard to claim 9, teaches the through hole is a plurality of through holes.

In regard to claim 10, teaches the surface where the element is formed of a semiconductor element is fixed on the one side of the substrate of the semiconductor package via a tape-like bonding material.

In regard to claim 11, Fukutomi teaches the surface where the element is formed of a semiconductor element is fixed on the one side of the substrate of the semiconductor package with adhesive at column 6, lines 66-67 to column 7, lines 1-2.

In regard to claim 12, Fukutomi teaches the surface where the element is formed of the semiconductor element is fixed on the one side of the substrate semiconductor package via a tape-like bonding material at column 20, lines 35-39, claim 11.

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In regard to claim 13, teaches the surface where the element is formed of a semiconductor element is fixed on the one side of the substrate semiconductor package via a tape-like bonding material at column 20, lines 35-39, claim 11.

In regard to claim 14, Fukutomi teaches the surface where the element is formed of a semiconductor element is fixed on the one side of the substrate of semiconductor package with adhesive at column 6, lines 66-67 to column 7, lines 1-2 and 20-27.

In regard to claim 15, Fukutomi teaches the surface where the element is formed of a semiconductor element is fixed on the one side of the substrate of the semiconductor package with adhesive at column 6, lines 66-67 to column 7, lines 1-2 and 20-27.

Conclusion

6. Any inquiry concerning this communication or earlier communications from the examiner should be directed to R. R. Berry whose telephone number is (703) 305-4544.



RRB

December 17, 2001



David Nelms
Supervisory Patent Examiner
Technology Center 2800